

A¹
4) A method according to claim 1 wherein the substrate is composed of plural layers.

A²
6) A method according to claim 4 wherein each said layer comprises different materials or combinations of materials.

A³
8) A method according to claim 1 including the additional step of optically monitoring the cutting region, the cutting process being controlled in response to the said optical monitoring.

A⁴
12) Apparatus according to claim 1 wherein the substrate is composed of plural layers.

A⁵
14) Apparatus according to claim 9 wherein at least two of the said laser beams provide laser light having different parameters.

A⁶
16) Apparatus according to claim 12 wherein each said layer comprises different materials or combinations of materials.

A⁷
18) Apparatus according to claim 9 wherein beam splitter means are provided so that at least two laser beams are derived from the same laser source.

19) Apparatus according to claim 9 wherein optical monitoring means are provided for optically monitoring the cutting region, means being provided to control the cutting process in response to the said optical monitoring

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